



TotalEnergies

Refining & Chemicals
Polymers

Polyethylene Aceso® HDPE 5502 R3

Technical data sheet
High Density Polyethylene BLOW MOULDING
Produced in Europe

Description

Aceso® HDPE 5502 R3 is a high density polyethylene (HDPE) with good compromise between stiffness and Environmental Stress Crack Resistance (ESCR). It has been specifically designed for the manufacture of blow molded packaging for pharmaceutical products and cosmetics liquids. However it is recommended to contact your local sales representative to obtain specific information and individual certificates regarding compliance to regulations.

Aceso® HDPE 5502 R3 is a pellet grade and contains antioxidants.

Characteristics

Property	Method	Unit	Typical value (*)
Density	ISO 1183	g/cm ³	0.954
Melt Flow Rate (190°C/21.6 kg)	ISO 1133/G	g/10 min	22
ESCR Antarox 100%	ASTM D 1693B	h	F ₅₀ = 60
Notched Charpy Impact Resistance 23°C	ISO 179-1	kJ/m ²	16

(*) Data not intended for specification purposes

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

Polyethylene

Information contained in this publication is true and accurate at the time of publication and to the best of our knowledge. The nominal values stated herein are obtained using laboratory test specimens. These are typical values not to be construed as specification limits. Before using one of the products mentioned herein, customers and other users should take all care in determining the suitability of such product for the intended use. Unless specifically indicated, the products mentioned herein are not suitable for applications in the pharmaceutical or medical sector. The Companies within TotalEnergies Petrochemicals do not accept any liability whatsoever arising from the use of this information or the use, application or processing of any product described herein. No information contained in this publication can be considered as a suggestion to infringe patents. The Companies disclaim any liability that may be claimed for infringement or alleged infringement of patents.

